

ABSTRACT

WORKPIECE PROCESSING METHOD

In a processing method according to the present invention, a surface protective tape peeling step of peeling a surface protective tape off the top surface of a wafer is performed in a state in which an expanding sheet is expanded while a preliminary expanding step of expanding the expanding sheet is performed after an affixing step is performed. Therefore, the surface protective tape can be peeled off the top surface of the wafer while a tension is applied to the expanding sheet. It is thereby possible to prevent chips from coming into contact with each other and being damaged. When an expanding step is thereafter performed, the expanding sheet is expanded by an amount of expansion which amount is a value larger than an amount of expansion of the expanding sheet in the preliminary expanding step. Thus, sufficient intervals can be formed between the chips, and the chips can be transported smoothly.

(Figure 11)